Title (en)

METHOD FOR PRODUCING A CIRCUIT BOARD ASSEMBLY, AND CIRCUIT BOARD ASSEMBLY

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER LEITERPLATTENANORDNUNG UND LEITERPLATTENANORDNUNG

Title (fr)

PROCÉDÉ DE FABRICATION D'UN ENSEMBLE CARTE DE CIRCUIT IMPRIMÉ ET ENSEMBLE CARTE DE CIRCUIT IMPRIMÉ

Publication

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Application

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Abstract (en)

[origin: WO2020053160A1] The invention relates to a method for producing a circuit board assembly (3), comprising the steps: providing a first circuit board substrate (1); providing a second circuit board substrate (2), which is arranged substantially plane-parallel to the first circuit board substrate (1), the first circuit board substrate (1) having a bottom side (11) and the second circuit board substrate (2) having a surface (12), the surface (12) and the bottom side (11) being arranged facing one another; providing first connection contacts (14), which are applied to the bottom side (11) of the first circuit board substrate (1); providing second connection contacts, which are applied to the surface (12) of the second circuit board substrate (2); applying solder paste cylinders (7) to the first connection contacts (14), the solder paste cylinders (7) being applied to the first connection contacts (14) by means of a solder paste application method with solder paste, the applied solder paste cylinders (7) each having a solder paste cylinder surface; and arranging the second connection contacts (4) of the second circuit board substrate (2) on the solder paste cylinder surfaces of the solder paste cylinders (7). The invention further relates to a circuit board assembly.

IPC 8 full level

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CPC (source: EP US)

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Citation (search report)

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